

Title (en)
ENCAPSULATED OPTOELECTRONIC SEMICONDUCTOR COMPONENT

Title (de)
VERGOSSENES OPTOELEKTRONISCHES HALBLEITERBAUELEMENT

Title (fr)
COMPOSANT SEMI-CONDUCTEUR OPTOÉLECTRONIQUE ENCAPSULÉ

Publication
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Application
EP 09799360 A 20091223

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Abstract (en)
[origin: WO2010102685A1] The invention relates to an optoelectronic semiconductor component (100) having - a carrier (1) comprising a mounting surface (11) and at least one penetration (3), wherein the penetration (3) extends from the mounting surface (11) to a base surface (12) of the carrier opposite the mounting surface (11); - at least one optoelectronic semiconductor chip (2) mounted on the mounting surface (11); - a cast body (5) transparent to radiation enclosing the at least one optoelectronic semiconductor chip (2) at least in places, wherein - the cast body (5) is disposed at least in places in the penetration (3) of the carrier (1).

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See references of WO 2010102685A1

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JP 2007027433 A 20070201 - MITSUBISHI CABLE IND LTD

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